

Product	Pr	oduct Dimensio	ons	Solder Weight	Recovered I.D.	СМА
Name	L	øA	øB	Milligrams	max	Range*
	max	min	min			
D-144-41	26.8	1.9	2.4	42±6	1.27	600 - 1600
	(1.055)	(0.075)	(0.095)		(0.050)	
D-144-47	26.8	3.8	4.5	118±16	2.16	2800 - 4000
	(1.055)	(0.150)	(0.177)		(0.085)	
D-144-48	26.8	3.8	4.5	176±24	2.16	3800 - 7500
	(1.055)	(0.150)	(0.177)		(0.085)	

\* Not all combinations of wires equalling listed CMA's will fit in sleeve.

A and B dimensions are measured through the sealing ring closest to that end.

## MATERIALS

- 1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked polyvinylidene fluoride.
- 2. SOLDER PREFORM WITH FLUX: (see table for weights)
  - SOLDER: TYPE Sn63 per ANSI J-STD-006.
  - FLUX: TYPE ROL0 per ANSI J-STD-004.
- 3. MELTABLE RINGS: Fluorocarbon-based thermoplastic. Color: gray.

## **APPLICATION**

1. These parts are designed for use in making in-line splices in wires having tin or silver plated conductors and insulations rated for 135°C minimum, meeting the dimensional criteria listed. See table for applicable size ranges.

2. Parts are designed for installation with TE Connectivity-approved infrared heaters. They may also be installed with convection heaters equipped with the correct reflector. The use of a holding fixture will aid in holding the assembly alignment when heating sleeve.

- 3. Parts will provide environmental protection on splices having no more than 2 wires per side.
- 4. For ease of inspection, it is recommended that the splice contain no more than 4 wires.
- 5. All wires are to be stripped 12.7±1.27 (.50±.05) and overlapped under solder preform.

Raychem THERMOFIT DEVICES			HERMOFIT	TITLE: SOLDERSLEEVE* SPLICE					
Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets]				DOCUMENT NO.: D-144-41/-47/-48					
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES ROUGHN MICRON	NESS IN	TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		REV:	2	DATE:	DATE: 09-Mar-2020	
		DATE: 27-Sep	ECO: pt-2000 ECO-20-003687		SCALE:	NTS	SIZE: A	SHEET: 1 of 1	

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